ON Semiconductor

Is Now

Onsemi

To learn more about onsemi[™], please visit our website at <u>www.onsemi.com</u>

onsemi and ONSEMI: and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product factures, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application is the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application, Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application, Buyer shall indemnify and hold ons

EMI Filter with ESD Protection for MicroSD Card Applications

Product Description

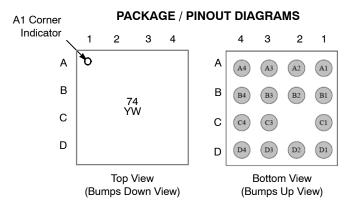
The EMI7403 is a combination EMI filter with integrated TVS diodes for use on Multimedia Card interfaces. This state-of-the-art device utilizes solid-state, silicon- avalanche technology for superior clamping performance and DC electrical characteristics. The EMI7403 has been optimized for protection of MicroSD interfaces in smart phones and other portable electronics.

Features

- Provides ESD Protection to IEC61000-4-2: ±15 kV Contact Discharge
- Protection and Termination for 6 Lines + V_{CC}
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- MicroSD Interfaces
- MMC Interfaces
- Feature Phones, Smart Phones





ON Semiconductor®

http://onsemi.com

		MARKING DIAGRAM
	WLCSP15 CASE 567FX	° 74 YW ▪
74 Y	= Specific Devi = Year	ice Code
W	= Work Week	

- = Work Week
- = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
EMI7403FCTBG	WLCSP15 (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

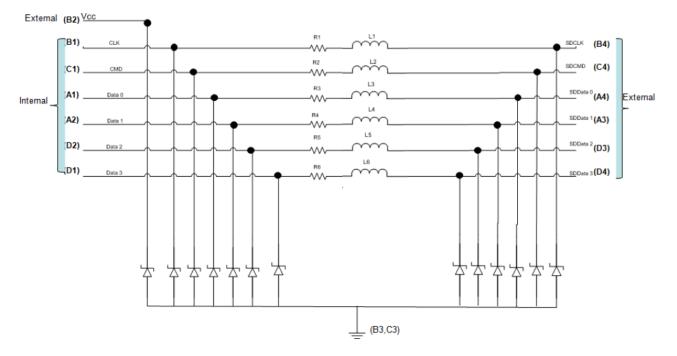


Figure 1. Electrical Schematic

Table 1. PIN DESCRIPTIONS

Pin	Description	Pin	Description	Pin	Description	Pin	Description
A1	data0 Internal	B1	clk Internal	C1	cmd Internal	D1	data3 Internal
A2	data1 Internal	B2	V _{CC} External			D2	data2 Internal
A3	SDdata1 External	B3	GND	C3	GND	D3	SDdata2 External
A4	SDdata0 External	B4	SDclk External	C4	SDcmd External	D4	SDdata3 External

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND OPERATING CONDITIONS

Parameter	Rating	Unit
Storage Temperature Range	–55 to +150	°C
Operating Temperature Range	-40 to +85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

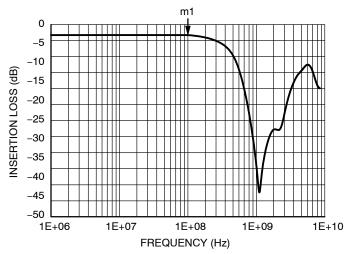
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _{RWM}	Reverse Working Voltage	(Note 3)		3.3		V
V_{BR}	Breakdown Voltage	I _T = 1 mA; (Note 4)	6.0		9.0	V
I _{LEAK}	Channel Leakage Current	V _{IN} = 3.3 V		0.1	0.5	μA
R _{CH}	Channel Resistance (R1 to R6)			40		Ω
f _{3dB}	Cut-off Frequency	50 Ω Source and Load Termination		300		MHz
F _{atten}	Stop Band Attenuation	@ 700 MHz @ 900 MHz		20 35		dB
V _{ESD}	In-system ESD Withstand Voltage a) Contact discharge per IEC 61000-4-2 standard, Level 4 (External Pins) b) Contact discharge per IEC 61000-4-2 standard, Level 1 (Internal Pins)	(Notes 1 and 2)	±15 ±2			kV

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics for the instear test conditions, unless otherwise notes. Treater performance may not be indicated by the Electrical Characteristics if operated under different conditions.
1. Standard IEC61000-4-2 with C_{Discharge} = 150 pF, R_{Discharge} = 330, GND grounded.
2. These measurements performed with no external capacitor.
3. TVS devices are normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal to or greater than the DC

or continuous peak operating voltage level.

4. V_{BR} is measured at pulse test current I_T.

RF CHARACTERISTICS



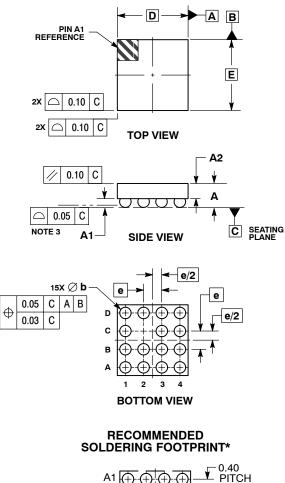


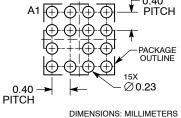
Interface	Data Rate (Mbyte/s)	Fundamental Frequency (MHz)	EMI7403 Insertion Loss (dB)
DDR50/SDR50	50	100 (m1)	m1 = 3.27





SCALE 4.1





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DATE 07 JUN 2012

NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

CROWNS OF SOLDER B				
	MILLIMETERS			
DIM	MIN MAX			
Α	0.47	0.53		
A1	0.185 0.205			
A2	0.305 REF 0.24 0.29 1.56 BSC			
b				
D				
E	1.56 BSC			
е	0.40 BSC			

GENERIC **MARKING DIAGRAM***



XX = Specific Device Code

= Year Υ

W = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " .", may or may not be present.

DOCUMENT NUMBER:	98AON81359E	AON81359E Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	WLCSP15, 1.56X1.56 PAGE		PAGE 1 OF 1		
ON Semiconductor and I are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.					

WLCSP15, 1.56x1.56 CASE 567FX ISSUE O

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor and the support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconducts harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized claim alleges that

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

TECHNICAL SUPPORT

ON Semiconductor Website: www.onsemi.com

North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative

٥